

System for Substrate Processing with Meniscus, Vacuum, IPA vapor, Drying Manifold

ABSTRACT OF THE DISCLOSURE

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An apparatus and method for processing a wafer is provided. The system and method are designed to process a surface of a wafer using a meniscus. The meniscus is controlled and is capable of being moved over the surface of the wafer to enable cleaning,
10 rinsing, chemical processing, and drying. The apparatus can be defined using a number of configurations to enable specific processing of the wafer surface using the meniscus, and such configurations can include the use of proximity heads.

Fig. 8A